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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	12V1
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, IrDA, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	40
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	3.13V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s12g64f0vlf

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1.3.1 S12 16-Bit Central Processor Unit (CPU)

S12 CPU is a high-speed 16-bit processing unit:

- Full 16-bit data paths supports efficient arithmetic operation and high-speed math execution
- Includes many single-byte instructions. This allows much more efficient use of ROM space.
- Extensive set of indexed addressing capabilities, including:
 - Using the stack pointer as an indexing register in all indexed operations
 - Using the program counter as an indexing register in all but auto increment/decrement mode
 - Accumulator offsets using A, B, or D accumulators
 - Automatic index predecrement, preincrement, postdecrement, and postincrement (by -8 to +8)

1.3.2 On-Chip Flash with ECC

On-chip flash memory on the MC9S12G-Family family features the following:

- Up to 240 Kbyte of program flash memory
 - 32 data bits plus 7 syndrome ECC (error correction code) bits allow single bit error correction and double fault detection
 - Erase sector size 512 bytes
 - Automated program and erase algorithm
 - User margin level setting for reads
 - Protection scheme to prevent accidental program or erase
- Up to 4 Kbyte EEPROM
 - 16 data bits plus 6 syndrome ECC (error correction code) bits allow single bit error correction and double fault detection
 - Erase sector size 4 bytes
 - Automated program and erase algorithm
 - User margin level setting for reads

1.3.3 On-Chip SRAM

• Up to 11 Kbytes of general-purpose RAM

1.3.4 Port Integration Module (PIM)

- Data registers and data direction registers for ports A, B, C, D, E, T, S, M, P, J and AD when used as general-purpose I/O
- Control registers to enable/disable pull devices and select pullups/pulldowns on ports T, S, M, P, J and AD on per-pin basis
- Single control register to enable/disable pull devices on ports A, B, C, D and E, on per-port basis and on BKGD pin
- Control registers to enable/disable open-drain (wired-or) mode on ports S and M

1.7.3.6 Power and Ground Connection Summary

Table	1-7.	Power	and	Ground	Connection	Summary
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Mnemonic	Nominal Voltage	Description
VDDR	3.15V – 5.0 V	External power supply for internal voltage regulator.
VSS	0V	Return ground for the logic supply generated by the internal regulator
VDDX _[3:1]	3.15V – 5.0 V	External power supply for I/O drivers. The 100-pin package features 3 I/O supply pins.
VSSX _[3:1]	0V	Return ground for I/O drivers. The100-pin package provides 3 ground pins
VDDX	3.15V – 5.0 V	External power supply for I/O drivers, All packages except 100-pin feature 1 I/O supply.
VSSX	0V	Return ground for I/O drivers. All packages except 100-pin provide 1 I/O ground pin.
VDDA	3.15V – 5.0 V	External power supply for the analog-to-digital converter and for the reference circuit of the internal voltage regulator.
VSSA	0V	Return ground for VDDA analog supply
VDDXR	3.15V – 5.0 V	External power supply for I/O drivers and internal voltage regulator. For the 48-pin package the VDDX and VDDR supplies are combined on one pin.
VDDXRA	3.15V – 5.0 V	External power supply for I/O drivers, internal voltage regulator and analog-to-digital converter. For the 20- and 32-pin package the VDDX, VDDR and VDDA supplies are combined on one pin.
VSSXA	0V	Return ground for I/O driver and VDDA analog supply
VRH	3.15V – 5.0 V	Reference voltage for the analog-to-digital converter.

	Function <lowestpriorityhighest></lowestpriorityhighest>				Power	Internal P Resisto	ull r	
Package Pin	Pin	2nd Func.	3rd Func.	4th Func	5th Func	Supply	CTRL	Reset State
28	PT4	IOC4	—	_	—	V _{DDX}	PERT/PPST	Disabled
29	PT3	IOC3	—	—	—	V _{DDX}	PERT/PPST	Disabled
30	PT2	IOC2	—	_	—	V _{DDX}	PERT/PPST	Disabled
31	PT1	IOC1	ĪRQ	_	—	V _{DDX}	PERT/PPST	Disabled
32	PT0	IOC0	XIRQ	_	—	V _{DDX}	PERT/PPST	Disabled
33	PAD0	KWAD0	AN0	_	—	V _{DDA}	PER1AD/PPS1AD	Disabled
34	PAD8	KWAD8	AN8	_	—	V _{DDA}	PER0AD/PPS0AD	Disabled
35	PAD1	KWAD1	AN1	_	—	V _{DDA}	PER1AD/PPS1AD	Disabled
36	PAD9	KWAD9	AN9	ACMPO	—	V _{DDA}	PER0ADPPS0AD	Disabled
37	PAD2	KWAD2	AN2	_	_	V _{DDA}	PER1AD/PPS1AD	Disabled
38	PAD10	KWAD10	AN10	ACMPP		V _{DDA}	PER0AD/PPS0AD	Disabled
39	PAD3	KWAD3	AN3	_	_	V _{DDA}	PER1AD/PPS1AD	Disabled
40	PAD11	KWAD11	AN11	ACMPM		V _{DDA}	PER0AD/PPS0AD	Disabled
41	PAD4	KWAD4	AN4	_	—	V _{DDA}	PER1AD/PPS1AD	Disabled
42	PAD12	KWAD12	—	_	—	V _{DDA}	PER0AD/PPS0AD	Disabled
43	PAD5	KWAD5	AN5	_	_	V _{DDA}	PER1AD/PPS1AD	Disabled
44	PAD13	KWAD13	—	_	—	V _{DDA}	PER0AD/PPS0AD	Disabled
45	PAD6	KWAD6	AN6	_	—	V _{DDA}	PER1AD/PPS1AD	Disabled
46	PAD14	KWAD14	—	_	—	V _{DDA}	PER0AD/PPS0AD	Disabled
47	PAD7	KWAD7	AN7	_	—	V _{DDA}	PER1AD/PPS1AD	Disabled
48	PAD15	KWAD15	—	_	—	V _{DDA}	PER0AD/PPS0AD	Disabled
49	VRH	_		_	_	_	_	_
50	VDDA	_		_	_	_	_	_
51	VSSA	_		_	_	_	_	_
52	PS0	RXD0		_	_	V _{DDX}	PERS/PPSS	Up
53	PS1	TXD0		_	_	V _{DDX}	PERS/PPSS	Up
54	PS2	RXD1	_	_	—	V _{DDX}	PERS/PPSS	Up
55	PS3	TXD1	_	—	—	V _{DDX}	PERS/PPSS	Up
56	PS4	MISO0	—	_	_	V _{DDX}	PERS/PPSS	Up

Table 1-17. 64-Pin LQFP Pinout for S12G48 and S12G64

2.5.2.6 Wired-Or Mode Register (WOMx)

If the pin is used as an output this register turns off the active-high drive. This allows wired-or type connections of outputs.

2.5.2.7 Interrupt Enable Register (PIEx)

If the pin is used as an interrupt input this register serves as a mask to the interrupt flag to enable/disable the interrupt.

2.5.2.8 Interrupt Flag Register (PIFx)

If the pin is used as an interrupt input this register holds the interrupt flag after a valid pin event.

2.5.2.9 Pin Routing Register (PRRx)

This register allows software re-configuration of the pinouts for specific peripherals in the 20 TSSOP package only.

2.5.2.10 Package Code Register (PKGCR)

This register determines the package in use. Pre programmed by factory.

2.5.3 Pin Configuration Summary

The following table summarizes the effect of the various configuration bits, that is data direction (DDR), output level (IO), pull enable (PE), pull select (PS) on the pin function and pull device ¹.

The configuration bit PS is used for two purposes:

- 1. Configure the sensitive interrupt edge (rising or falling), if interrupt is enabled.
- 2. Select either a pullup or pulldown device if PE is active.

^{1.}

Table 7-6. Firmware Commands				
Command ¹	Opcode (hex)	Data	Description	
READ_NEXT ²	62	16-bit data out	Increment X index register by 2 (X = X + 2), then read word X points to.	
READ_PC	63	16-bit data out	Read program counter.	
READ_D	64	16-bit data out	Read D accumulator.	
READ_X	65	16-bit data out	Read X index register.	
READ_Y	66	16-bit data out	Read Y index register.	
READ_SP	67	16-bit data out	Read stack pointer.	
WRITE_NEXT ²	42	16-bit data in	Increment X index register by 2 (X = X + 2), then write word to location pointed to by X.	
WRITE_PC	43	16-bit data in	Write program counter.	
WRITE_D	44	16-bit data in	Write D accumulator.	
WRITE_X	45	16-bit data in	Write X index register.	
WRITE_Y	46	16-bit data in	Write Y index register.	
WRITE_SP	47	16-bit data in	Write stack pointer.	
GO	08	none	Go to user program. If enabled, ACK will occur when leaving active background mode.	
GO_UNTIL ³	0C	none	Go to user program. If enabled, ACK will occur upon returning to active background mode.	
TRACE1	10	none	Execute one user instruction then return to active BDM. If enabled, ACK will occur upon returning to active background mode.	
TAGGO -> GO	18	none	(Previous enable tagging and go to user program.)	

If enabled, ACK will occur when data is ready for transmission for all BDM READ commands and will occur after the write is complete for all BDM WRITE commands.

Opcode will be executed as a GO command.

This command will be deprecated and should not be used anymore.

2 When the firmware command READ NEXT or WRITE NEXT is used to access the BDM address space the BDM resources are accessed rather than user code. Writing BDM firmware is not possible.

3 System stop disables the ACK function and ignored commands will not have an ACK-pulse (e.g., CPU in stop or wait mode). The GO UNTIL command will not get an Acknowledge if CPU executes the wait or stop instruction before the "UNTIL" condition (BDM active again) is reached (see Section 7.4.7, "Serial Interface Hardware Handshake Protocol" last note).

7.4.5 **BDM Command Structure**

Hardware and firmware BDM commands start with an 8-bit opcode followed by a 16-bit address and/or a 16-bit data word, depending on the command. All the read commands return 16 bits of data despite the byte or word implication in the command name.

> 8-bit reads return 16-bits of data, only one byte of which contains valid data. If reading an even address, the valid data will appear in the MSB. If reading an odd address, the valid data will appear in the LSB.

> > MC9S12G Family Reference Manual Rev.1.27

10.1.3 S12CPMU Block Diagram



Figure 10-1. Block diagram of S12CPMU

MC9S12G Family Reference Manual Rev.1.27



Read: Anytime

Write: LVIE and LVIF are write anytime, LVDS is read only

Field	Description
2 LVDS	 Low-Voltage Detect Status Bit — This read-only status bit reflects the voltage level on VDDA. Writes have no effect. Input voltage VDDA is above level V_{LVID} or RPM. Input voltage VDDA is below level V_{LVIA} and FPM.
1 LVIE	Low-Voltage Interrupt Enable Bit 0 Interrupt request is disabled. 1 Interrupt will be requested whenever LVIF is set.
0 LVIF	 Low-Voltage Interrupt Flag — LVIF is set to 1 when LVDS status bit changes. This flag can only be cleared by writing a 1. Writing a 0 has no effect. If enabled (LVIE = 1), LVIF causes an interrupt request. 0 No change in LVDS bit. 1 LVDS bit has changed.

Table 10-15. CPMULVCTL Field Descriptions

10.3.2.14 Autonomous Periodical Interrupt Control Register (CPMUAPICTL)

The CPMUAPICTL register allows the configuration of the autonomous periodical interrupt features.





Read: Anytime

MC9S12G Family Reference Manual Rev.1.27

- 4. Clear all flags in the CPMUFLG register to be able to detect any future status bit change.
- 5. Optionally status interrupts can be enabled (CPMUINT register).

Loosing PLL lock status (LOCK=0) means loosing the oscillator status information as well (UPOSC=0).

The impact of loosing the oscillator status (UPOSC=0) in PEE mode is as follows:

- The PLLCLK is derived from the VCO clock (with its actual frequency) divided by four until the PLL locks again.
- The OSCCLK provided to the MSCAN module is off.

Application software needs to be prepared to deal with the impact of loosing the oscillator status at any time.

10.4.6.3 PLL Bypassed External Mode (PBE)

In this mode, the Bus Clock is based on the external oscillator clock. The reference clock for the PLL is based on the external oscillator.

The clock sources for COP and RTI can be based on the internal reference clock generator or on the external oscillator clock or the RC-Oscillator (ACLK).

This mode can be entered from default mode PEI by performing the following steps:

- 1. Make sure the PLL configuration is valid.
- 2. Enable the external oscillator (OSCE bit)
- 3. Wait for the oscillator to start-up and the PLL being locked (LOCK = 1) and (UPOSC = 1).
- 4. Clear all flags in the CPMUFLG register to be able to detect any status bit change.
- 5. Optionally status interrupts can be enabled (CPMUINT register).
- 6. Select the Oscillator Clock (OSCCLK) as Bus Clock (PLLSEL=0)

Loosing PLL lock status (LOCK=0) means loosing the oscillator status information as well (UPOSC=0).

The impact of loosing the oscillator status (UPOSC=0) in PBE mode is as follows:

- PLLSEL is set automatically and the Bus Clock is switched back to the PLLCLK.
- The PLLCLK is derived from the VCO clock (with its actual frequency) divided by four until the PLL locks again.
- The OSCCLK provided to the MSCAN module is off.

Application software needs to be prepared to deal with the impact of loosing the oscillator status at any time.

Analog-to-Digital Converter (ADC12B16CV2)

¹If only AN0 should be converted use MULT=0.

16.3.2.2 ATD Control Register 1 (ATDCTL1)

Writes to this register will abort current conversion sequence.

Module Base + 0x0001



Figure 16-4. ATD Control Register 1 (ATDCTL1)

Read: Anytime

Write: Anytime

Table 16-	3. ATDCTL1	Field	Descriptions
10010 10			

Field	Description
7 ETRIGSEL	External Trigger Source Select — This bit selects the external trigger source to be either one of the AD channels or one of the ETRIG3-0 inputs. See device specification for availability and connectivity of ETRIG3-0 inputs. If a particular ETRIG3-0 input option is not available, writing a 1 to ETRISEL only sets the bit but has no effect, this means that one of the AD channels (selected by ETRIGCH3-0) is configured as the source for external trigger. The coding is summarized in Table 16-5.
6–5 SRES[1:0]	A/D Resolution Select — These bits select the resolution of A/D conversion results. See Table 16-4 for coding.
4 SMP_DIS	 Discharge Before Sampling Bit No discharge before sampling. The internal sample capacitor is discharged before sampling the channel. This adds 2 ATD clock cycles to the sampling time. This can help to detect an open circuit instead of measuring the previous sampled channel.
3–0 ETRIGCH[3:0]	External Trigger Channel Select — These bits select one of the AD channels or one of the ETRIG3-0 inputs as source for the external trigger. The coding is summarized in Table 16-5.

SRES1	SRES0	A/D Resolution
0	0	8-bit data
0	1	10-bit data
1	0	12-bit data
1	1	Reserved

20.4.4 Baud Rate Generation

A 13-bit modulus counter in the baud rate generator derives the baud rate for both the receiver and the transmitter. The value from 0 to 8191 written to the SBR12:SBR0 bits determines the bus clock divisor. The SBR bits are in the SCI baud rate registers (SCIBDH and SCIBDL). The baud rate clock is synchronized with the bus clock and drives the receiver. The baud rate clock divided by 16 drives the transmitter. The receiver has an acquisition rate of 16 samples per bit time.

Baud rate generation is subject to one source of error:

• Integer division of the bus clock may not give the exact target frequency.

Table 20-16 lists some examples of achieving target baud rates with a bus clock frequency of 25 MHz.

When IREN = 0 then,

SCI baud rate = SCI bus clock / (16 * SCIBR[12:0])

Bits SBR[12:0]	Receiver Clock (Hz)	Transmitter Clock (Hz)	Target Baud Rate	Error (%)
41	609,756.1	38,109.8	38,400	.76
81	308,642.0	19,290.1	19,200	.47
163	153,374.2	9585.9	9,600	.16
326	76,687.1	4792.9	4,800	.15
651	38,402.5	2400.2	2,400	.01
1302	19,201.2	1200.1	1,200	.01
2604	9600.6	600.0	600	.00
5208	4800.0	300.0	300	.00

Table 20-16. Baud Rates (Example: Bus Clock = 25 MHz)



All bits in the FRSV3 register read 0 and are not writable.

25.3.2.15 Flash Reserved4 Register (FRSV4)

This Flash register is reserved for factory testing.





All bits in the FRSV4 register read 0 and are not writable.

25.3.2.16 Flash Option Register (FOPT)

The FOPT register is the Flash option register.





¹ Loaded from IFR Flash configuration field, during reset sequence.

All bits in the FOPT register are readable but are not writable.

During the reset sequence, the FOPT register is loaded from the Flash nonvolatile byte in the Flash configuration field at global address $0x_3$ _FF0E located in P-Flash memory (see Table 25-4) as indicated by reset condition F in Figure 25-22. If a double bit fault is detected while reading the P-Flash phrase containing the Flash nonvolatile byte during the reset sequence, all bits in the FOPT register will be set.

Global Address Range	Protected Size
0x3_F800-0x3_FFFF	2 Kbytes
0x3_F000-0x3_FFFF	4 Kbytes
0x3_E000-0x3_FFFF	8 Kbytes
0x3_C000-0x3_FFFF	16 Kbytes
	Global Address Range 0x3_F800-0x3_FFFF 0x3_F000-0x3_FFFF 0x3_E000-0x3_FFFF 0x3_C000-0x3_FFFF

Tahla	27-10	D -Flach	Protection	Highor	Addrage	Range
lanc	21-13.	1 -1 10311	TIOLECTION	Ingher	Audiess	Nange

Table 27-20. P-Flash Protection Lower Address Range

FPLS[1:0]	Global Address Range	Protected Size
00	0x3_8000-0x3_83FF	1 Kbyte
01	0x3_8000-0x3_87FF	2 Kbytes
10	0x3_8000-0x3_8FFF	4 Kbytes
11	0x3_8000-0x3_9FFF	8 Kbytes

All possible P-Flash protection scenarios are shown in Figure 27-14. Although the protection scheme is loaded from the Flash memory at global address 0x3_FFOC during the reset sequence, it can be changed by the user. The P-Flash protection scheme can be used by applications requiring reprogramming in single chip mode while providing as much protection as possible if reprogramming is not required.

64 KByte Flash Module (S12FTMRG64K1V1)

FCMD	Command	Function on P-Flash Memory
0x02	Erase Verify Block	Verify that a P-Flash block is erased.
0x03	Erase Verify P-Flash Section	Verify that a given number of words starting at the address provided are erased.
0x04	Read Once	Read a dedicated 64 byte field in the nonvolatile information register in P-Flash block that was previously programmed using the Program Once command.
0x06	Program P-Flash	Program a phrase in a P-Flash block.
0x07	Program Once	Program a dedicated 64 byte field in the nonvolatile information register in P-Flash block that is allowed to be programmed only once.
0x08	Erase All Blocks	Erase all P-Flash (and EEPROM) blocks. An erase of all Flash blocks is only possible when the FPLDIS, FPHDIS, and FPOPEN bits in the FPROT register and the DPOPEN bit in the EEPROT register are set prior to launching the command.
0x09	Erase Flash Block	Erase a P-Flash (or EEPROM) block. An erase of the full P-Flash block is only possible when FPLDIS, FPHDIS and FPOPEN bits in the FPROT register are set prior to launching the command.
0x0A	Erase P-Flash Sector	Erase all bytes in a P-Flash sector.
0x0B	Unsecure Flash	Supports a method of releasing MCU security by erasing all P-Flash (and EEPROM) blocks and verifying that all P-Flash (and EEPROM) blocks are erased.
0x0C	Verify Backdoor Access Key	Supports a method of releasing MCU security by verifying a set of security keys.
0x0D	Set User Margin Level	Specifies a user margin read level for all P-Flash blocks.
0x0E	Set Field Margin Level	Specifies a field margin read level for all P-Flash blocks (special modes only).

Table 27-28. P-Flash Commands

27.4.4.5 EEPROM Commands

Table 27-29 summarizes the valid EEPROM commands along with the effects of the commands on the EEPROM block.

Table 27-29	. EEPROM	Commands
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FCMD	Command	Function on EEPROM Memory
0x01	Erase Verify All Blocks	Verify that all EEPROM (and P-Flash) blocks are erased.
0x02	Erase Verify Block	Verify that the EEPROM block is erased.

Register	Error Bit	Error Condition
		Set if CCOBIX[2:0] != 101 at command launch
	ACCERR	Set if command not available in current mode (see Table 27-27)
	ACCERK	Set if an invalid phrase index is supplied
FSTAT		Set if the requested phrase has already been programmed ¹
	FPVIOL	None
	MGSTAT1	Set if any errors have been encountered during the verify operation
	MGSTAT0	Set if any non-correctable errors have been encountered during the verify operation

Table 27-43. Program Once Command Error Handling

27.4.6.7 Erase All Blocks Command

The Erase All Blocks operation will erase the entire P-Flash and EEPROM memory space.

Table 27-44. Erase All Blocks Command FCCOB Requirements

CCOBIX[2:0]	FCCOB Parameters		
000	0x08	Not required	

Upon clearing CCIF to launch the Erase All Blocks command, the Memory Controller will erase the entire Flash memory space and verify that it is erased. If the Memory Controller verifies that the entire Flash memory space was properly erased, security will be released. During the execution of this command (CCIF=0) the user must not write to any Flash module register. The CCIF flag will set after the Erase All Blocks operation has completed.

Register	Error Bit	Error Condition	
	ACCEPR	Set if CCOBIX[2:0] != 000 at command launch	
	ACCERK	Set if command not available in current mode (see Table 27-27)	
FSTAT	FPVIOL	Set if any area of the P-Flash or EEPROM memory is protected	
	MGSTAT1	Set if any errors have been encountered during the verify operation	
	MGSTAT0	Set if any non-correctable errors have been encountered during the verify operation	

Table 27-45. Erase All Blocks Command Error Handling

27.4.6.8 Erase Flash Block Command

The Erase Flash Block operation will erase all addresses in a P-Flash or EEPROM block.

28.4.8 Wait Mode

The Flash module is not affected if the MCU enters wait mode. The Flash module can recover the MCU from wait via the CCIF interrupt (see Section 28.4.7, "Interrupts").

28.4.9 Stop Mode

If a Flash command is active (CCIF = 0) when the MCU requests stop mode, the current Flash operation will be completed before the MCU is allowed to enter stop mode.

28.5 Security

The Flash module provides security information to the MCU. The Flash security state is defined by the SEC bits of the FSEC register (see Table 28-11). During reset, the Flash module initializes the FSEC register using data read from the security byte of the Flash configuration field at global address 0x3_FF0F. The security state out of reset can be permanently changed by programming the security byte assuming that the MCU is starting from a mode where the necessary P-Flash erase and program commands are available and that the upper region of the P-Flash is unprotected. If the Flash security byte is successfully programmed, its new value will take affect after the next MCU reset.

The following subsections describe these security-related subjects:

- Unsecuring the MCU using Backdoor Key Access
- Unsecuring the MCU in Special Single Chip Mode using BDM
- Mode and Security Effects on Flash Command Availability

28.5.1 Unsecuring the MCU using Backdoor Key Access

The MCU may be unsecured by using the backdoor key access feature which requires knowledge of the contents of the backdoor keys (four 16-bit words programmed at addresses 0x3_FF00-0x3_FF07). If the KEYEN[1:0] bits are in the enabled state (see Section 28.3.2.2), the Verify Backdoor Access Key command (see Section 28.4.6.11) allows the user to present four prospective keys for comparison to the keys stored in the Flash memory via the Memory Controller. If the keys presented in the Verify Backdoor Access Key command match the backdoor keys stored in the Flash memory, the SEC bits in the FSEC register (see Table 28-11) will be changed to unsecure the MCU. Key values of 0x0000 and 0xFFFF are not permitted as backdoor keys. While the Verify Backdoor Access Key command is active, P-Flash memory and EEPROM memory will not be available for read access and will return invalid data.

Register	Error Bit	Error Condition
		Set if CCOBIX[2:0] != 001 at command launch
	ACCERR	Set if command not available in current mode (see Table 29-27)
	ACCERK	Set if an invalid FlashBlockSelectionCode[1:0] is supplied (See Table 29-34)
FSTAT		Set if an invalid margin level setting is supplied
	FPVIOL	None
	MGSTAT1	None
	MGSTAT0	None

Table 29-59. Set Field Margin Level Command Error Handling

CAUTION

Field margin levels must only be used during verify of the initial factory programming.

NOTE

Field margin levels can be used to check that Flash memory contents have adequate margin for data retention at the normal level setting. If unexpected results are encountered when checking Flash memory contents at field margin levels, the Flash memory contents should be erased and reprogrammed.

29.4.6.14 Erase Verify EEPROM Section Command

The Erase Verify EEPROM Section command will verify that a section of code in the EEPROM is erased. The Erase Verify EEPROM Section command defines the starting point of the data to be verified and the number of words.

CCOBIX[2:0]	FCCOB Parameters		
000	0x10	Global address [17:16] to identify the EEPROM block	
001	Global address [15:0] of the first word to be verified		
010	Number of words to be verified		

Table 29-60. Erase Verify EEPROM Section Command FCCOB Requirements

Upon clearing CCIF to launch the Erase Verify EEPROM Section command, the Memory Controller will verify the selected section of EEPROM memory is erased. The CCIF flag will set after the Erase Verify EEPROM Section operation has completed. If the section is not erased, it means blank check failed, both MGSTAT bits will be set.

192 KByte Flash Module (S12FTMRG192K2V1)

reprogrammed to the unsecure state, if desired. In the unsecure state, the user has full control of the contents of the backdoor keys by programming addresses 0x3_FF00-0x3_FF07 in the Flash configuration field.

30.5.2 Unsecuring the MCU in Special Single Chip Mode using BDM

A secured MCU can be unsecured in special single chip mode by using the following method to erase the P-Flash and EEPROM memory:

- 1. Reset the MCU into special single chip mode
- 2. Delay while the BDM executes the Erase Verify All Blocks command write sequence to check if the P-Flash and EEPROM memories are erased
- 3. Send BDM commands to disable protection in the P-Flash and EEPROM memory
- 4. Execute the Erase All Blocks command write sequence to erase the P-Flash and EEPROM memory. Alternatively the Unsecure Flash command can be executed, if so the steps 5 and 6 below are skeeped.
- 5. After the CCIF flag sets to indicate that the Erase All Blocks operation has completed, reset the MCU into special single chip mode
- 6. Delay while the BDM executes the Erase Verify All Blocks command write sequence to verify that the P-Flash and EEPROM memory are erased

If the P-Flash and EEPROM memory are verified as erased, the MCU will be unsecured. All BDM commands will now be enabled and the Flash security byte may be programmed to the unsecure state by continuing with the following steps:

- 7. Send BDM commands to execute the Program P-Flash command write sequence to program the Flash security byte to the unsecured state
- 8. Reset the MCU

30.5.3 Mode and Security Effects on Flash Command Availability

The availability of Flash module commands depends on the MCU operating mode and security state as shown in Table 30-27.

30.6 Initialization

On each system reset the flash module executes an initialization sequence which establishes initial values for the Flash Block Configuration Parameters, the FPROT and EEPROT protection registers, and the FOPT and FSEC registers. The initialization routine reverts to built-in default values that leave the module in a fully protected and secured state if errors are encountered during execution of the reset sequence. If a double bit fault is detected during the reset sequence, both MGSTAT bits in the FSTAT register will be set.

CCIF is cleared throughout the initialization sequence. The Flash module holds off all CPU access for a portion of the initialization sequence. Flash reads are allowed once the hold is removed. Completion of the initialization sequence is marked by setting CCIF high which enables user commands.





Table 31-5. Program IFR Fields

Global Address	Size (Bytes)	Field Description
0x0_4000 - 0x0_4007	8	Reserved
0x0_4008 – 0x0_40B5	174	Reserved
0x0_40B6 - 0x0_40B7	2	Version ID ¹

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Cond	Conditions are 3.13V < V _{DD35} < 5.5 V unless otherwise noted.							
Nu m	С	Rating	Symbol	Min	Тур	Мах	Unit	
1	М	Port J, P, AD interrupt input pulse filtered (STOP) ¹	t _{P_MASK}	_	—	3	μS	
2	М	Port J, P, AD interrupt input pulse passed (STOP) ¹	t _{P_PASS}	10	—	—	μS	
3	D	Port J, P, AD interrupt input pulse filtered ($\overline{\text{STOP}}$) in number of bus clock cycles of period $1/f_{\text{bus}}$	n _{P_MASK}	_	_	3		
4	D	Port J, P, AD interrupt input pulse passed ($\overline{\text{STOP}}$) in number of bus clock cycles of period $1/f_{bus}$	n _{P_PASS}	4	—	—		
5	D	$\overline{\text{IRQ}}$ pulse width, edge-sensitive mode ($\overline{\text{STOP}}$) in number of bus clock cycles of period 1/f _{bus}	n _{IRQ}	1	—	—		

Table A-11. Pin Interrupt Characteristics (Junction Temperature From +150°C To +160°C)

¹ Parameter only applies in stop or pseudo stop mode.

A.3 Supply Currents

This section describes the current consumption characteristics of the device as well as the conditions for the measurements.

A.3.1 Measurement Conditions

Run current is measured on the VDDX, VDDR¹, and VDDA² pins. It does not include the current to drive external loads. Unless otherwise noted the currents are measured in special single chip mode and the CPU code is executed from RAM. For Run and Wait current measurements PLL is on and the reference clock is the IRC1M trimmed to 1MHz. The bus frequency is 25MHz and the CPU frequency is 50MHz. Table A-12., Table A-13. and Table A-14. show the configuration of the CPMU module and the peripherals for Run, Wait and Stop current measurement.

Fable A-12. CPMU Configur	ation for Pseudo Stop	Current Measurement
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CPMU REGISTER	Bit settings/Conditions				
CPMUCLKS	PLLSEL=0, PSTP=1, PRE=PCE=RTIOSCSEL=COPOSCSEL=1				

1. On some packages VDDR is bonded to VDDX and the pin is named

VDDXR. Refer to Section 1.8, "Device Pinouts" for further details.

^{2.} On some packages VDDA is connected with VDDXR and the common pin

is named VDDXRA.On some packages VSSA is connected to VSSX and the common pin is named

VSSXA. See section Section 1.8, "Device Pinouts" for further details.

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0x026A	DDRJ	R W	DDRJ7	DDRJ6	DDRJ5	DDRJ4	DDRJ3	DDRJ2	DDRJ1	DDRJ0
0x026B	Reserved	R	0	0	0	0	0	0	0	0
		W								
0x026C	PERJ	R W	PERJ7	PERJ6	PERJ5	PERJ4	PERJ3	PERJ2	PERJ1	PERJ0
0x026D	PPSJ	R W	PPSJ7	PPSJ6	PPSJ5	PPSJ4	PPSJ3	PPSJ2	PPSJ1	PPSJ0
0x026E	PIEJ	R W	PIEJ7	PIEJ6	PIEJ5	PIEJ4	PIEJ3	PIEJ2	PIEJ1	PIEJ0
0x026F	PIFJ	R W	PIFJ7	PIFJ6	PIFJ5	PIFJ4	PIFJ3	PIFJ2	PIFJ1	PIFJ0
0x0270	PT0AD	R W	PT0AD7	PT0AD6	PT0AD5	PT0AD4	PT0AD3	PT0AD2	PT0AD1	PT0AD0
0x0271	PT1AD	R W	PT1AD7	PT1AD6	PT1AD5	PT1AD4	PT1AD3	PT1AD2	PT1AD1	PT1AD0
0x0272	PTI0AD	R W	PTI0AD7	PTI0AD6	PTI0AD5	PTI0AD4	PTI0AD3	PTI0AD2	PTI0AD1	PTI0AD0
0x0273	PTI1AD	R W	PTI1AD7	PTI1AD6	PTI1AD5	PTI1AD4	PTI1AD3	PTI1AD2	PTI1AD1	PTI1AD0
0x0274	DDR0AD	R W	DDR0AD7	DDR0AD6	DDR0AD5	DDR0AD4	DDR0AD3	DDR0AD2	DDR0AD1	DDR0AD0
0x0275	DDR1AD	R W	DDR1AD7	DDR1AD6	DDR1AD5	DDR1AD4	DDR1AD3	DDR1AD2	DDR1AD1	DDR1AD0

0x0262–0x0275 Port Integration Module (PIM) Map 5 of 6

0x0276 Reference Voltage Attenuator (RVA)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
0x0276	RVACTL	RVACTI R	RVACTI R		R	0	0	0	0	0	0	0	
		W								INVAOIN			

0x0277–0x027F Port Integration Module (PIM) Map 6 of 6

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
0x0277	PRR1	R	0	0	0	0	0	0	0	PRR1AN	
0.0211		W									
0x0278	PER0AD	R	PER0AD7	PER0AD6	PER0AD5	PER0AD4	PER0AD3	PER0AD2	PER0AD1	PER0AD0	
		W									
0x0279	PFR1AD	R	PER1AD7	PER1AD6	PER1AD5	PFR1AD4	PER1AD3	PER1AD2	PFR1AD1	PER1AD0	
000210			W						T EI(II)(DE		
∩v027∆	ΡΡςήδη	R					PPS0AD3			PPS0AD0	
0,0217	TT OUAD	TT SUAD	W						11 OUADZ		
0v027B		R									
UNU27D	TIGIAD	W	11 STADI	11 STADO	TT STADS	11 STAD4	11 STADS	11 STADZ	TISIADI	TT STADU	